# 2SD1458

## Silicon NPN epitaxial planar type

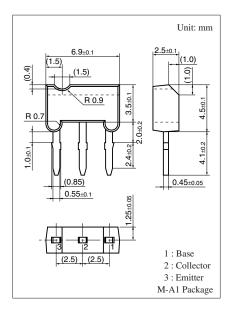
For low-frequency amplification

#### Features

- $\bullet$  High forward current transfer ratio  $h_{FE}$
- Low collector-emitter saturation voltage V<sub>CE(sat)</sub>
- M type package allowing easy automatic and manual insertion as well as stand-alone fixing to the printed circuit board.

Parameter	Symbol	Rating	Unit					
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	20	V					
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	20	V					
Emitter-base voltage (Collector open)	V <sub>EBO</sub>	15	V					
Collector current	I <sub>C</sub>	0.7	А					
Peak collector current	I <sub>CP</sub>	1.5	А					
Collector power dissipation *	P <sub>C</sub>	1	W					
Junction temperature	Tj	150	°C					
Storage temperature	T <sub>stg</sub>	-55 to +150	°C					





Note) \*: Printed circuit board: Copper foil area of 1 cm<sup>2</sup> or more, and the board thickness of 1.7 mm for the collector portion

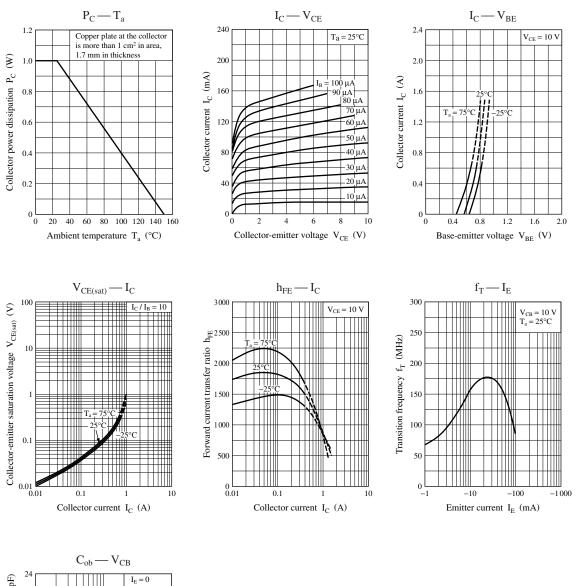
#### Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

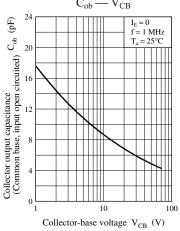
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	$I_{C} = 10 \ \mu A, \ I_{E} = 0$	20			V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_{C} = 1 \text{ mA}, I_{B} = 0$	20			V
Emitter-base voltage (Collector open)	V <sub>EBO</sub>	$I_E = 10 \ \mu A, \ I_C = 0$	15			V
Collector-base cutoff current (Emitter open)	I <sub>CBO</sub>	$V_{CB} = 15 \text{ V}, I_E = 0$			1	μΑ
Collector-emitter cutoff current (Base open)	I <sub>CEO</sub>	$V_{CE} = 15 \text{ V}, I_B = 0$			10	μΑ
Forward current transfer ratio *	h <sub>FE</sub>	$V_{CE} = 10 \text{ V}, \text{ I}_{C} = 150 \text{ mA}$	1 0 0 0		2 5 0 0	_
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	$I_{C} = 500 \text{ mA}, I_{B} = 50 \text{ mA}$			0.4	V
Transition frequency	f <sub>T</sub>	$V_{CB} = 20 \text{ V}, I_E = -20 \text{ mA}, f = 200 \text{ MHz}$		55		MHz
Collector output capacitance	C <sub>ob</sub>	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		11	15	pF
(Common base, input open circuited)						

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. \*: Pulse measurement

## Panasonic





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